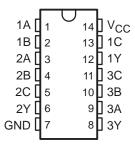
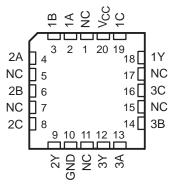
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 20-μA Max I<sub>CC</sub>

SN54HC27 ... J OR W PACKAGE SN74HC27 ... D, DB, N, OR NS PACKAGE (TOP VIEW)



- Typical t<sub>pd</sub> = 9 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max





NC - No internal connection

### description/ordering information

The 'HC27 devices contain three independent 3-input NOR gates. They perform the Boolean function  $Y = \overline{A} + \overline{B} + \overline{C}$  or  $Y = \overline{A} \bullet \overline{B} \bullet \overline{C}$  in positive logic.

#### ORDERING INFORMATION

TA	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PDIP – N	Tube of 25	SN74HC27N	SN74HC27N	
-40°C to 85°C		Tube of 50	SN74HC27D		
	SOIC - D	Reel of 2500	SN74HC27DR	HC27	
		Reel of 250	SN74HC27DT		
	SOP - NS	Reel of 2000	SN74HC27NSR	HC27	
	SSOP – DB	Reel of 2000	SN74HC27DBR	HC27	
	CDIP – J	Tube of 25	SNJ54HC27J	SNJ54HC27J	
–55°C to 125°C	CFP – W	Tube of 150	SNJ54HC27W	SNJ54HC27W	
	LCCC – FK	Tube of 55	SNJ54HC27FK	SNJ54HC27FK	

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

# FUNCTION TABLE (each gate)

	INPUTS	OUTPUT	
Α	В	С	Υ
Н	Х	Χ	L
Х	Н	Χ	L
Х	X	Н	L
L	L	L	Н



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#### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub>		
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CO}$ )		
Continuous output current, $I_O(V_O = 0)$ to $V_{CC}$		
Continuous current through V <sub>CC</sub> or GND		
Package thermal impedance, θ <sub>JA</sub> (see Note 2)		
5 1 7 6/11		
	N package	80°C/W
	NS package	
Storage temperature range, T <sub>stq</sub>		

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

#### recommended operating conditions (see Note 3)

			S	N54HC2	7	SN74HC27			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		2	5	6	2	5	6	V
		V <sub>CC</sub> = 2 V	1.5			1.5			
VIH	+	V <sub>CC</sub> = 4.5 V	3.15			3.15			V
		VCC = 6 V	4.2			4.2			
	Low-level input voltage	V <sub>CC</sub> = 2 V			0.5			0.5	
VIL		V <sub>CC</sub> = 4.5 V			1.35			1.35	V
		VCC = 6 V			1.8			1.8	
٧ <sub>I</sub>	Input voltage		0		VCC	0		VCC	V
٧o	Output voltage		0		VCC	0		VCC	V
		V <sub>CC</sub> = 2 V			1000			1000	
Δt/Δν	Input transition rise/fall time	V <sub>CC</sub> = 4.5 V			500			500	ns
		V <sub>CC</sub> = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		Vaa	Т	A = 25°C	;	SN54HC27		SN74HC27		шыт	
PARAMETER			VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
			2 V	1.9	1.998		1.9		1.9			
		I <sub>OH</sub> = -20 μA	4.5 V	4.4	4.499		4.4		4.4			
Voн	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V	
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		1 1	
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34			
	VI = VIH or VIL			2 V		0.002	0.1		0.1		0.1	
		$I_{OL} = 20  \mu A$	4.5 V		0.001	0.1		0.1		0.1		
V <sub>OL</sub>			6 V		0.001	0.1		0.1		0.1	V	
		$I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33		
			$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA	
Icc	$V_I = V_{CC}$ or 0,	I <sub>O</sub> = 0	6 V			2		40		20	μΑ	
Ci			2 V to 6 V		3	10		10		10	pF	

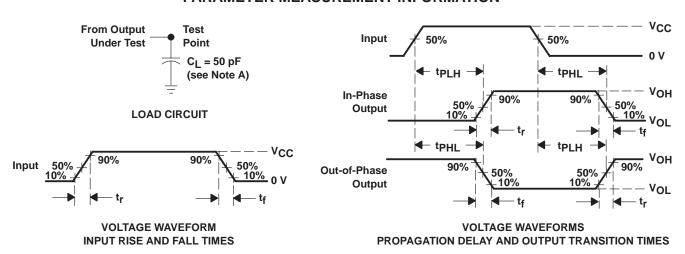
# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM TO		Vaa	Т,	Δ = 25°C	;	SN54l	HC27	SN74H	1C27	UNIT
PARAMETER	(INPUT)	(OUTPUT)	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		35	90		135		115	
t <sub>pd</sub>	A, B, or C	Y	4.5 V		10	18		27		23	ns
				L	6 V		9	15		23	
			2 V		27	75		110		95	
t <sub>t</sub>		Y	4.5 V		7	15		22		19	ns
				6 V		6	13		19		16

# operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance per gate	No load	25	pF

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f = 6 \ ns$ ,  $t_f = 6 \ ns$ .
- C. The outputs are measured one at a time with one input transition per measurement.
- D. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms







ti.com 6-Jun-2005

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finis	h MSL Peak Temp <sup>(3)</sup>
84042012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
8404201CA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
8404201DA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/65102BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54HC27J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN74HC27D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC27DBR	ACTIVE	SSOP	DB	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC27DBRE4	ACTIVE	SSOP	DB	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC27DE4	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC27DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC27DRE4	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC27DT	ACTIVE	SOIC	D	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC27DTE4	ACTIVE	SOIC	D	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC27N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HC27NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HC27NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC27NSRE4	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SNJ54HC27FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54HC27J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54HC27W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder



#### PACKAGE OPTION ADDENDUM

6-Jun-2005

temperature.

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## 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# W (R-GDFP-F14)

# CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



#### FK (S-CQCC-N\*\*)

#### **28 TERMINAL SHOWN**

#### **LEADLESS CERAMIC CHIP CARRIER**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



# D (R-PDSO-G14)

# PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



### **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



### DB (R-PDSO-G\*\*)

### PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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